

MATLAB EXPO

# Intel® Agilex™ 7 FPGA-in-the-Loop Simulation

Enabling DSP Emulation for Space-BACN

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# Outline

- DARPA Space-BACN Program
  - Overview
  - TA2 Requirements & DSP Considerations
- DSP Emulation Challenges and Solutions
  - MathWorks FPGA-in-the-Loop (FIL) Simulation
  - Intel® Agilex™ 7 FPGA I-Series
- FIL Architectures for Intel® Agilex™ 7 FPGA I-Series
  - Ethernet (via HPS) - Intel® Agilex™ 7 FPGA I-Series Transceiver-SoC Development Kit
  - PCI-Express - Intel® Agilex™ 7 FPGA I-Series Development Kit
- FIL Simulation Demo
  - LTE Turbo Decoder
  - Results

# DARPA Space-BACN Program

Space-Based Adaptive Communications Node (Space-BACN) program aims to create a reconfigurable intersatellite optical communications terminal that is low size, weight, power, and cost (SWaP-C), and easy to integrate.

It allows seamless communication between heterogeneous constellations that operate on different optical intersatellite link (OISL) specifications, and which otherwise would not be able to communicate.

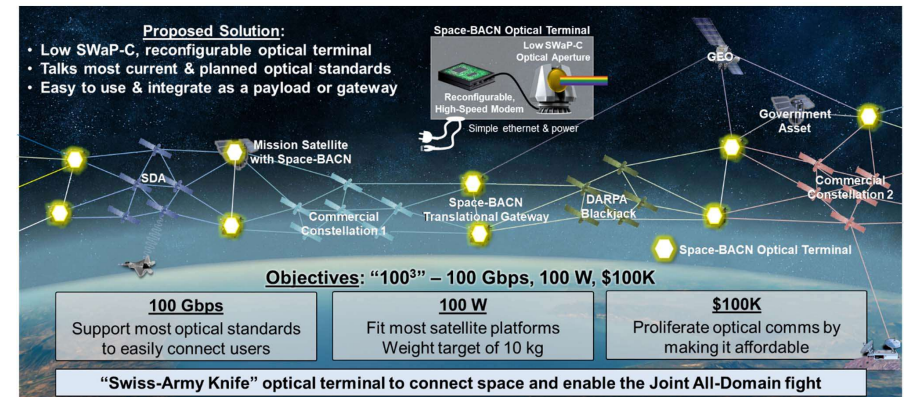
The program objectives are summarized as “100 Cubed”:

- 100 Gbps to support most optical standards.
- 100W or less to minimize power consumption.
- Under \$100K to make it affordable.

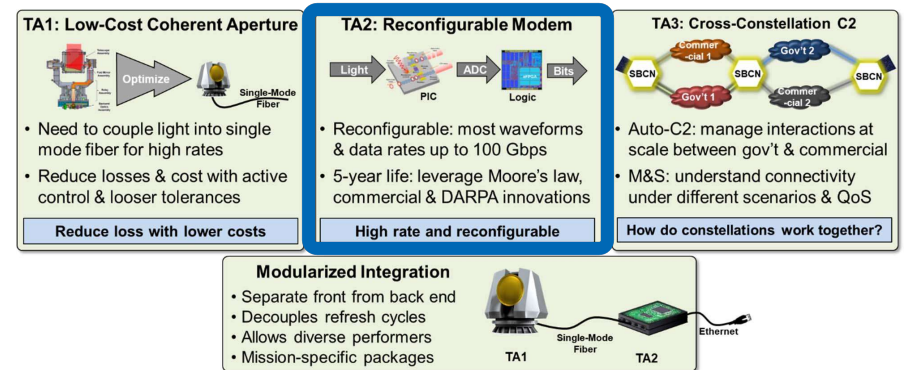
Space-BACN will focus on three key technical areas:

- A low-cost, optical aperture capable of coupling into single mode fiber Lower-risk design integration (TA1).
- A reconfigurable modem that can support multiple optical waveforms up to 100 Gbps (TA2).
- A novel cross-constellation command and control approach to automate interactions between government and commercial satellites (TA3).

<https://www.darpa.mil/work-with-us/space-based-adaptive-communications-node>



Space-BACN program overview



Space-BACN program components

# TA2 Requirements & DSP Implementation Considerations

## Digital Signal Processing (DSP) Emulation Considerations:

- Modulation/Demodulation Formats
  - OOK, PPM, DPSK, BPSK, QPSK, and DP-QPSK
- Datarates
  - Up to 10Gbps OOK & Up to 100Gbps PSK
- Timing Recovery Loops
  - Clock Data Recovery (CDR)
  - Doppler + CDR
- FEC coding
  - DVB-S2 (LDPC+BCH), SDA (LDPC), OFEC (Turbo), CCSDS (RS, LDPC), G709 (RS)
- Post-FEC BER
  - $\leq 1E-15$

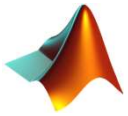
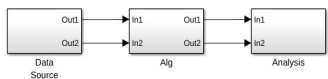
TA2 Metric	Phase 1	Phase 2
Supported modulation formats	Reconfigurable design for OOK, PPM, DPSK, BPSK, QPSK, and DP-QPSK	EDU reconfigurable for OOK, PPM, DPSK, BPSK, QPSK, and DP-QPSK
Baud rate	Programmable 1-33 GBaud	Programmable 1-33 GBaud
Supported data rates	Up to 10 Gbps OOK up to 100 Gbps PSK	Up to 10 Gbps OOK up to 100 Gbps PSK
<b>Transmitter</b>		
Tunable/selectable wavelength range	1,530 nm – 1,565 nm	1,530 nm – 1,565 nm
Laser RIN	-140 dB/Hz peak -145 dB/Hz average	-140 dB/Hz peak -145 dB/Hz average
Laser spectral linewidth	500 kHz	500 kHz
Optical output measured in SMF	0 dBm per polarization	0 dBm per polarization
TX OSNR	>30 dB/0.1 nm	>30 dB/0.1 nm
TX output polarization	PM-SMF	PM-SMF
<b>Receiver</b>		
Sensitivity at 100G	-18 dBm	-18 dBm
Post-FEC BER	$\leq 1E-15$	$\leq 1E-15$
Optical input	SMF	SMF
FEC coding supported (code rates $\geq 1/2$ )	DVB-S2 (LDPC+BCH), SDA (LDPC), OFEC (Turbo), CCSDS (RS, LDPC), G709 (RS)	Phase 1 + programmable to other variants
Doppler	Up to $\pm 50$ ppm	Up to $\pm 50$ ppm

Space-BACN program TA2 metrics

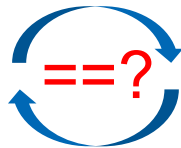
<https://sam.gov/opp/e704657b448649a4a5ff7debeb39540a/view>  
Space\_BACN\_Appendix\_amended\_20210927.pdf

# DSP Simulation Challenges and Solutions

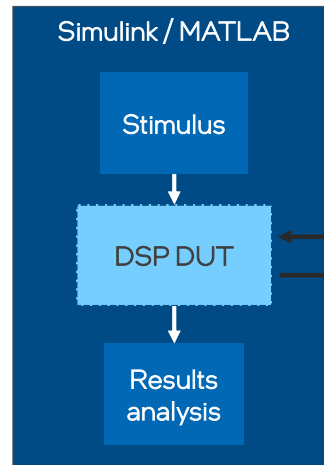
Does the design implemented in HDL match the specification?



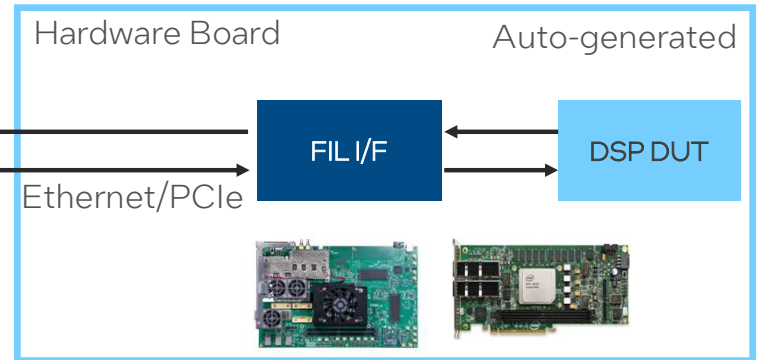
Algorithm Design as Specification



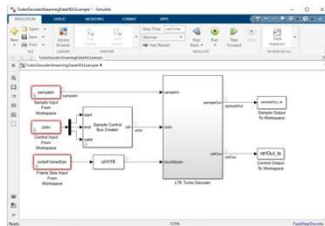
Implemented Hardware Design



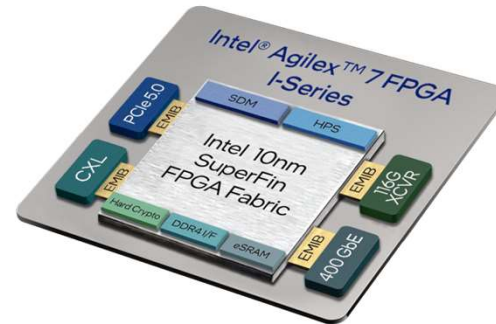
MATLAB/Simulink as Test Bench for Hardware IP FPGA-in-the-Loop (FIL)



Software simulation is SLOW!



Processing 16B+ samples of LTE Turbo Decoder test stimulus can take 21.5 days

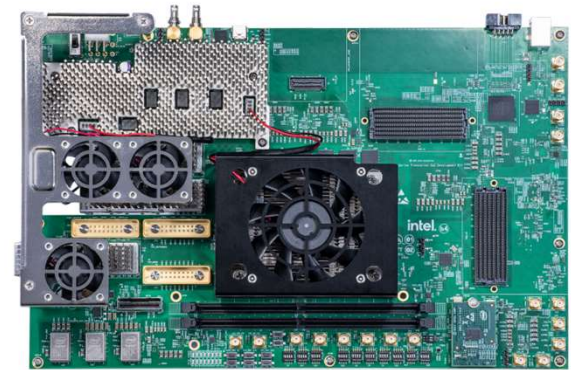
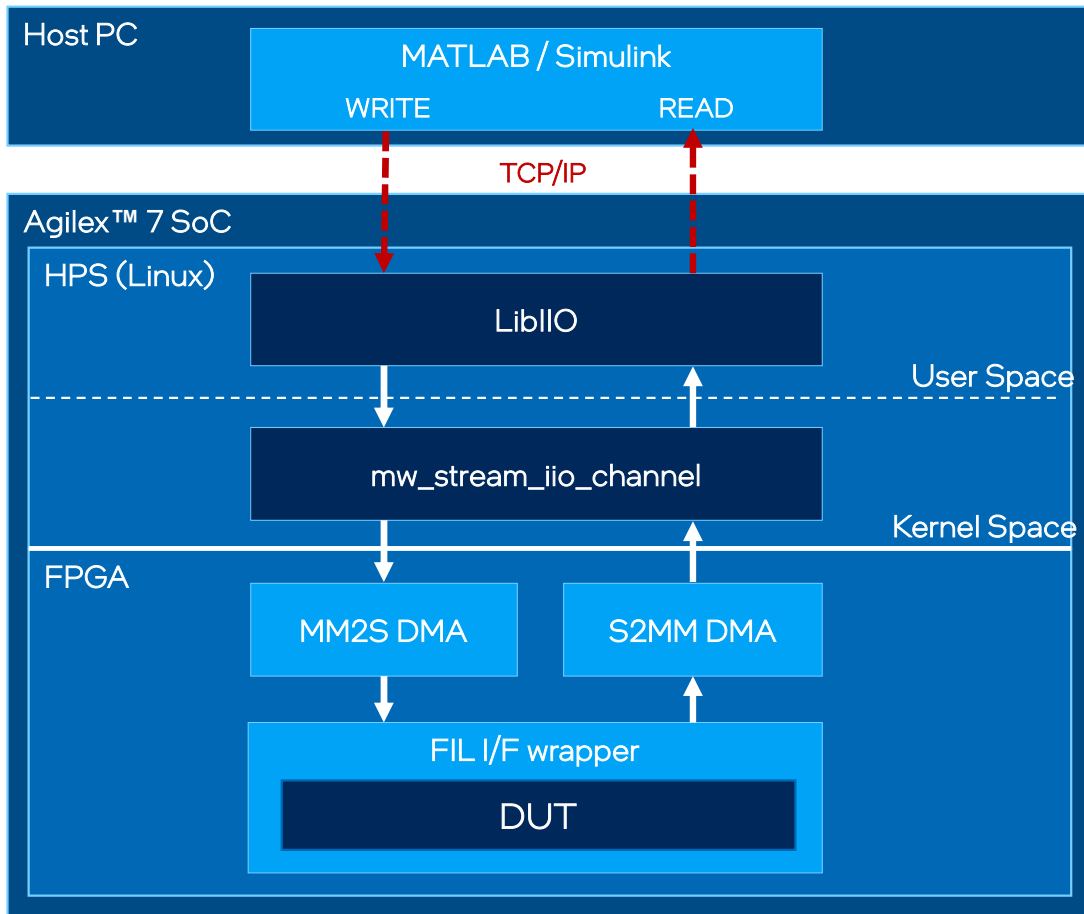


Relevant Key Features:

- PCI Express (PCIe) 5.0 Support
- Hard Processor System (HPS)
  - Quad-core Arm Cortex-A53
- AGI 027
  - 2700 KLE
  - DDR4

<https://www.intel.com/content/www/us/en/products/details/fpga/agilex/7/i-series.html>

# Ethernet FIL Architecture for Agilex

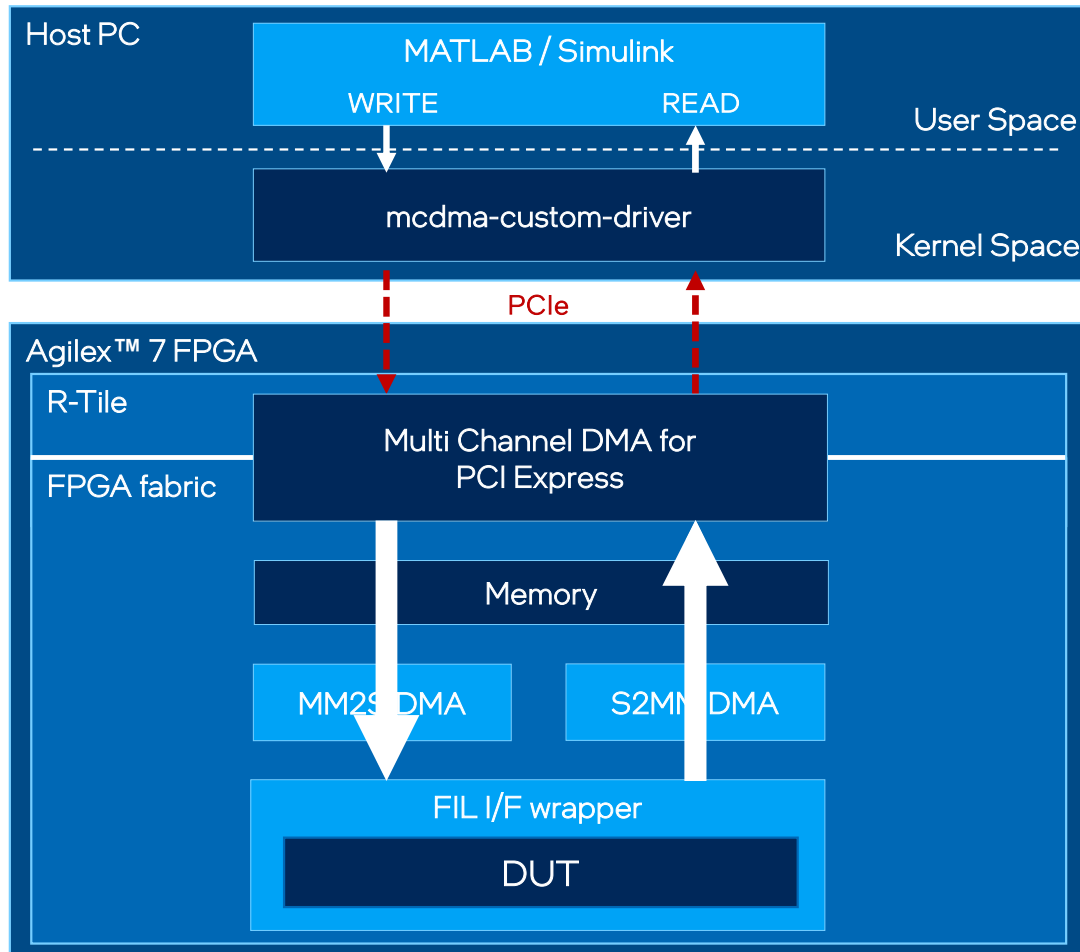


Intel® Agilex™ 7 FPGA I-Series Transceiver-SoC Development Kit (4x F-Tile) DK-SI-AGI027FB

<https://www.rocketboards.org/foswiki/Documentation/AgilexSoCGSRDSI/AGI027>

<https://github.com/mathworks/altera-linux/tree/mw-agilex-soc-5.15/drivers/misc/mathworks>

# PCI-Express FIL Architecture for Agilex (On-going)



Intel® Agilex™ 7 FPGA I-Series Development Kit (2x R-Tile and 1x F-Tile) DK-DEV-AGI027RIBES

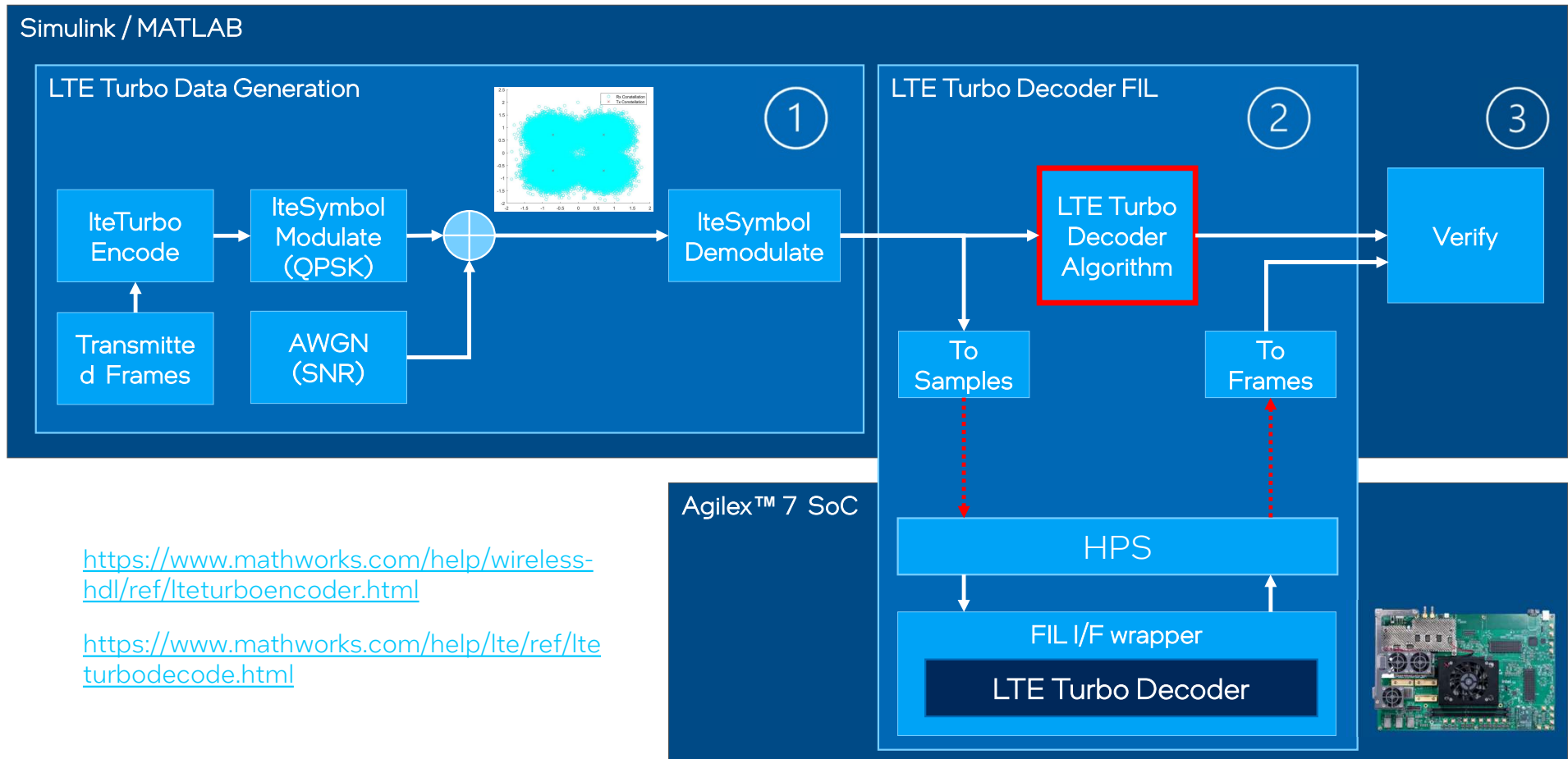
<https://www.intel.com/content/www/us/en/docs/programmable/683821/22-4/>

<https://www.intel.com/content/www/us/en/docs/programmable/683517/22-4/>



# FIL Simulation Demo - LTE Turbo Decoder

Simulink / MATLAB



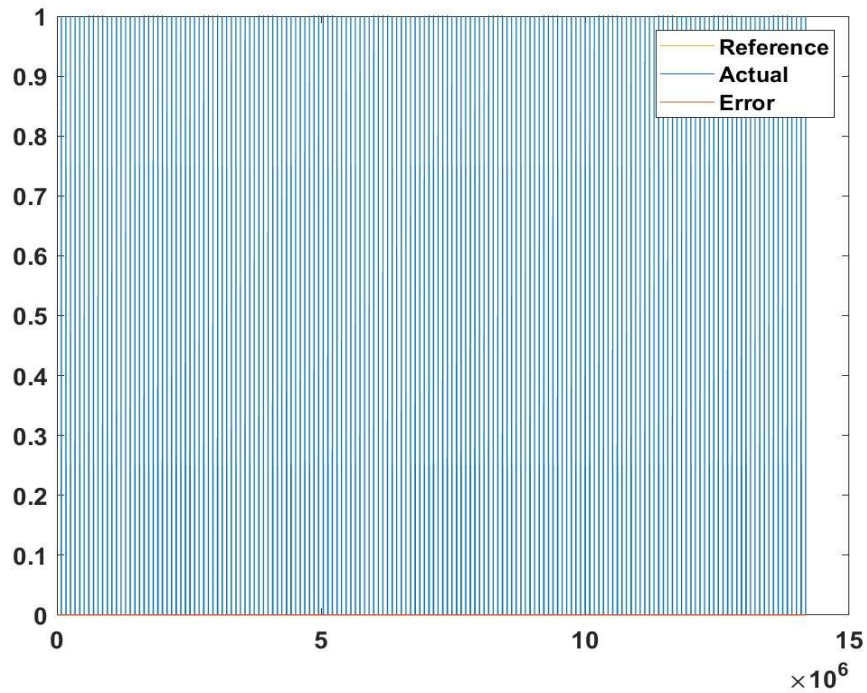
<https://www.mathworks.com/help/wireless-hdl/ref/lteTurboEncoder.html>

<https://www.mathworks.com/help/lte/ref/lteTurboDecoder.html>



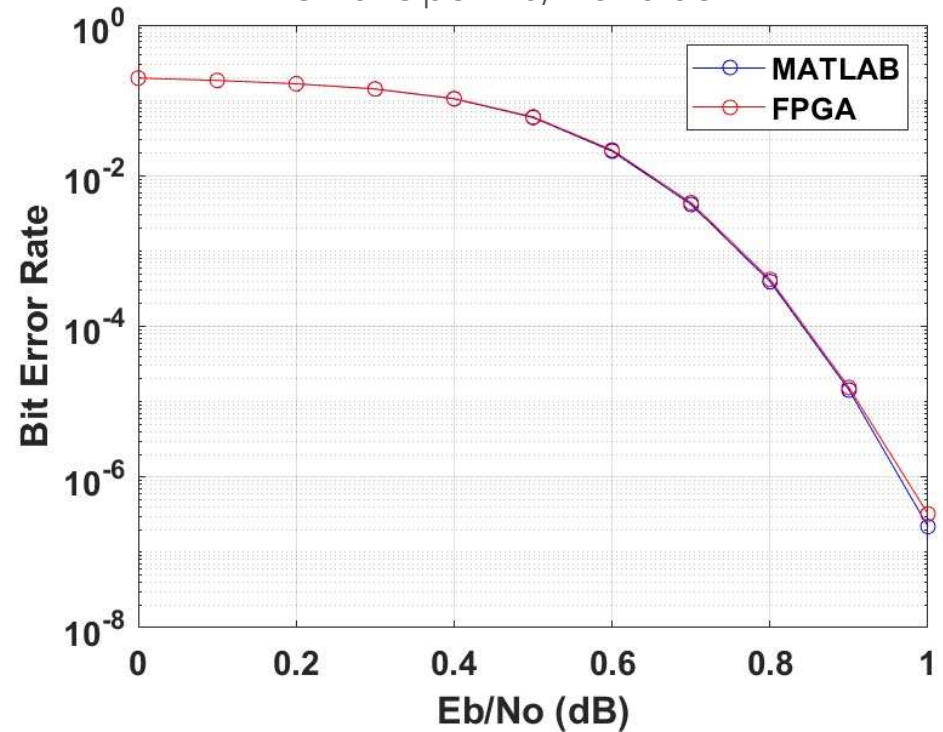
# FIL Simulation Demo - Results

Decoded bits - Sim vs. FIL (1e6 bits, Eb/No = 0.5)



- Bit and cycle accuracy between the hardware module and the source Simulink model used to generate the RTL code

1e9 bits per Eb/No value



- Simulation: 518 hours (21.5 days)
- FIL cycle accurate: 48 hours (2 days)
- FIL free running: 23 minutes

# Notices & Disclaimers

This research was, in part, funded by the U.S. Government under the DARPA Space-BACN program. The views and conclusions contained in this document are those of the authors and should not be interpreted as representing the official policies, either expressed or implied, of the U.S. Government.

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